

DESCRIPTION:

The *M-Densus* series is a family of interchangeable memory modules. The 64 Megabit DRAM is a member of this family which utilizes the new and innovative space saving TSOP technology. The modules are constructed with 16 Meg x 4 EDO, 3.3 Volt DRAM's available in 512, 256 and 128 Megabits.

The 64 Megabit based *M-Densus* modules have been designed to fit in the same footprint as the 16 Meg x 4 DRAM TSOP monolithic and are backward compatible with the 16 Megabit based family of *M-Densus* modules. This allows the memory board designer to upgrade the memory in their products without redesigning the memory board, thus saving time and money.

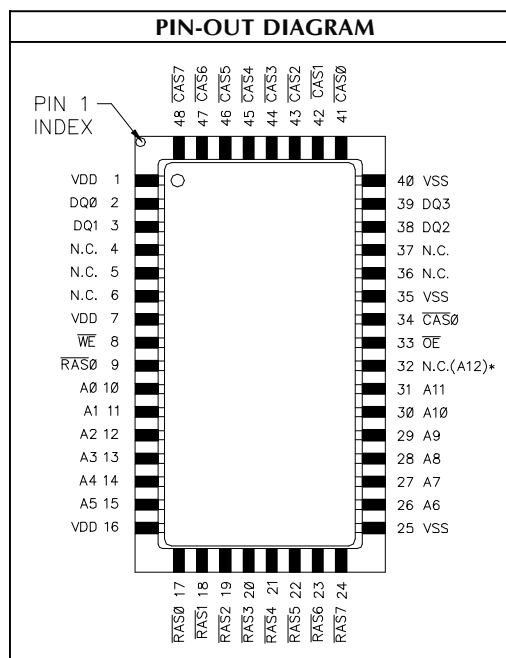
FEATURES:

- Configurations Available:
 - 128 Megabit: 32 Meg x 4
 - 256 Megabit: 64 Meg x 4
 - 512 Megabit: 128 Meg x 4
- Access Times: 50, 60, 70ns (max.)
- 3.3 Volt Supply
- Common Data Inputs and Outputs
- Extended Data Out Capability (EDO)
- 4K/8K 64ms Refresh
- 3 Variations of Refresh:
 - RAS only Refresh
 - CAS before RAS Refresh
 - Hidden Refresh
- Package: Leadless TSOP Module

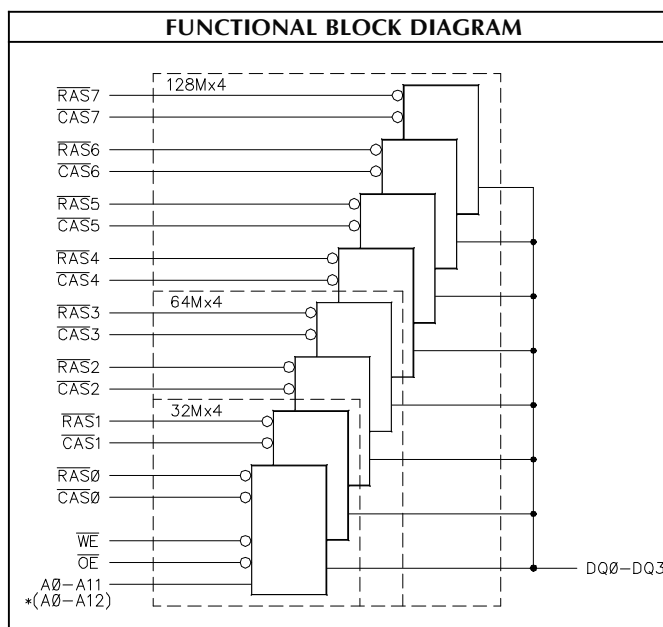
PIN NAMES	
A0 - A11	Row Address: A0 - A11 Column Address: A0 - A11 Refresh Address: A0 - A11
A0 - A12*	Row Address: A0 - A12 Column Address: A0 - A10 Refresh Address: A0 - A12
DQ0 - DQ3	Data In / Data Out
CAS0 - CAS7	Column Address Strokes
RAS0 - RAS7	Row Address Enables
WE	Data Write Enable
OE	Data Output Enable
VDD	Power Supply (+3.3V)
Vss	Ground
N.C.	No Connect

* A12 for 8K refresh device.

PIN-OUT DIAGRAM



FUNCTIONAL BLOCK DIAGRAM



PRELIMINARY

ABSOLUTE MAXIMUM RATINGS			
Symbol	Parameter	Value	Units
T _{STC}	Storage Temperature	-55 to +150	°C
V _{I/O}	Voltage on Any Pin	-0.5 to +6.5	V
V _{DD}	V _{DD} Supply Voltage	-0.5 to +4.6	V
I _{OUT}	Output Current	50	mA

* -1.3V at pulse width ≤ 15ns which is measured at V_{DD}.** 6.5V at pulse width ≤ 15ns which is measured at V_{DD}.

RECOMMENDED OPERATING CONDITIONS					
Symbol	Parameter	Min.	Typ.	Max.	Units
V _{DD}	Supply Voltage	3.0	3.3	3.6	V
V _{IL}	Input Low Voltage	-0.3*		0.8	V
V _{IH}	Input High Voltage	2.0		+5.5**	V
T _A	Operating Temperature	0	+25	+70	°C

NOTE: All voltages referenced to V_{SS}.

CAPACITANCE: t _A = 25°C, f = 1MHz						
Symbol	Parameter	32Mx4	64Mx4	128Mx4	Unit	Condition
C _{ADR}	Address Input	12	25	45	pF	V _{IN} = 0V
C _{CAS}	CAS Input	8	10	12		
C _{RAS}	RAS Input	8	10	12		
C _{WE}	Write Enable	15	30	60		
C _{OE}	Output Enable	15	30	60		
C _{I/O}	Data Input/Output	15	30	60		

DC INPUT/OUTPUT CHARACTERISTICS									
Symbol	Characteristic	Conditions	32Mx4		64Mx4		128Mx4		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
I _{IN}	Input Leakage Current	CAS, RAS A0-A11, WE, OE	-5	+5	-5	+5	-5	+5	μA
I _{OUT}	Output Leakage Current		-10	+10	-20	+20	-40	+40	μA
V _{OL}	Output Low Voltage	IOL = 4.2mA		0.4		0.4		0.4	V
V _{OH}	Output High Voltage	IOH = -5mA	2.4		2.4		2.4		V

DC OPERATING CHARACTERISTICS										
Symbol	Characteristic	Conditions		MAXIMUM						Units
				50ns		60ns		70ns		
				4K	8K	4K	8K	4K	8K	
I _{CC1}	Operating Current	$\overline{\text{RAS}}$ and $\overline{\text{CAS}}$ cycling @ t _{RC} = min.	32Mx4	152	102	142	92	132	82	mA
			64Mx4	156	106	146	96	136	86	
			128Mx4	164	114	154	104	144	94	
I _{CC2}	Standby Current	$\overline{\text{RAS}} = \overline{\text{CAS}} = \overline{\text{WE}} = V_{\text{IH}}$	32Mx4	4	4	4	4	4	4	mA
			64Mx4	8	8	8	8	8	8	
			128Mx4	16	16	16	16	16	16	
I _{CC3} *	$\overline{\text{RAS}}$ - Only Refresh Current	$\overline{\text{CAS}} = V_{\text{IH}}$, $\overline{\text{RAS}}$ Cycling @ t _{RC} = min.	32Mx4	152	102	142	92	132	82	mA
			64Mx4	156	106	146	96	136	86	
			128Mx4	164	114	154	104	144	94	
I _{CC4}	FAST-PAGE-MODE Current	$\overline{\text{RAS}} = V_{\text{IL}}$, $\overline{\text{CAS}}$, Address Cycling @ t _{PC} = min.	32Mx4	82	72	72	62	67	57	mA
			64Mx4	86	76	76	66	71	61	
			128Mx4	94	84	84	74	49	69	
I _{CC5}	Standby Current	$\overline{\text{RAS}} = \overline{\text{CAS}} = \overline{\text{WE}} = V_{\text{DD}} - 2.0\text{V}$	32Mx4	2	2	2	2	2	2	mA
			64Mx4	4	4	4	4	4	4	
			128Mx4	8	8	8	8	8	8	
I _{CC6} ***	$\overline{\text{CAS}}$ - Before - $\overline{\text{RAS}}$ Refresh Current	$\overline{\text{RAS}}$ and $\overline{\text{CAS}}$ Cycling @ t _{RC} = min.	32Mx4	152	152	142	142	132	132	mA
			64Mx4	156	156	146	146	136	136	
			128Mx4	164	164	154	154	144	144	

*** Assumes distributed refresh.

PRELIMINARY

A.C. OPERATING AND CHARACTERISTICS ($V_{CC} = 3.3V \pm 0.3V$, $T_A = 0^\circ C$ to $70^\circ C$)									
No.	Symbol	Parameter	50ns		60ns		70ns		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	
1	t _{RC}	Random Read or Write Cycle Time	90		110		125		ns
2	t _{RAC}	Access Time from $\overline{RAS}$ ^{3, 4, 10}		50		60		70	ns
3	t _{CAC}	Access Time from $\overline{CAS}$ ^{3, 4, 5}		13		15		20	ns
4	t _{AA}	Access Time from Column Address ^{3, 10}		25		30		35	ns
5	t _{CLZ}	$\overline{CAS}$ to Output in LOW-Z ³	3		3		3		ns
6	t _{CEZ}	Output Buffer Turn-Off Delay From $\overline{CAS}$ ^{6,12}	3	13	3	13	3	15	ns
7	t _T	Transition Time (rise and fall) ²	1	50	1	50	1	50	ns
8	t _{RP}	$\overline{RAS}$ Precharge Time	30		40		50		ns
9	t _{RAS}	$\overline{RAS}$ Pulse Width	50	10,000	60	10,000	70	10,000	ns
10	t _{RSH}	$\overline{RAS}$ Hold Time	13		15		20		ns
11	t _{CSH}	$\overline{CAS}$ Hold Time	38		45		55		ns
12	t _{CAS}	$\overline{CAS}$ Pulse Width ⁴	8	10,000	15	10,000	15	10,000	ns
13	t _{RCD}	$\overline{RAS}$ to $\overline{CAS}$ Delay Time ⁹	20	37	20	45	20	50	ns
14	t _{RAD}	$\overline{RAS}$ to Column Address Delay Time	15	25	15	30	15	35	ns
15	t _{CRP}	$\overline{CAS}$ to $\overline{RAS}$ Precharge Time	5		5		5		ns
16	t _{ASR}	Row Address Setup Time	0		0		0		ns
17	t _{RAH}	Row Address Hold Time	10		10		10		ns
18	t _{ASC}	Column Address Setup Time	0		0		0		ns
19	t _{CAH}	Column Address Hold Time	8		10		15		ns
20	t _{RAL}	Column Address to $\overline{RAS}$ Lead Time	25		30		40		ns
21	t _{RCS}	Read Command Setup Time	0		0		0		ns
22	t _{RCH}	Read Command Hold Time Referenced to $\overline{CAS}$ ⁸	0		0		0		ns
23	t _{RRH}	Read Command Hold Time Referenced to $\overline{RAS}$ ⁸	0		0		0		ns
24	t _{WCH}	Write Command Hold Time	10		10		15		ns
25	t _{WP}	Write Command Pulse Width	10		10		15		ns
26	t _{RWL}	Write Command to $\overline{RAS}$ Lead Time	13		15		25		ns
27	t _{CWL}	Write Command to $\overline{CAS}$ Lead Time	8		10		20		ns
28	t _{DS}	Data-In Setup Time ⁹	0		0		0		ns
29	t _{DH}	Data-In Hold Time ⁹	8		10		20		ns
30	t _{REF}	Refresh Period		64		64		64	ms
31	t _{WCS}	Write Command Setup Time ⁷	0		0		0		ns
32	t _{CSR}	$\overline{CAS}$ Set Up time ($\overline{CAS}$ Before $\overline{RAS}$ Refresh)	5		5		10		ns
33	t _{CHR}	$\overline{CAS}$ Hold Time ($\overline{CAS}$ Before $\overline{RAS}$ Refresh)	10		10		15		ns
34	t _{RPC}	$\overline{RAS}$ to $\overline{CAS}$ precharge time	5		5		5		ns
35	t _{CPA}	Access time From $\overline{CAS}$ Precharge ³		28		35		40	ns
36	t _{HPC}	Hyper Page Cycle Time ¹¹	25		30		35		ns

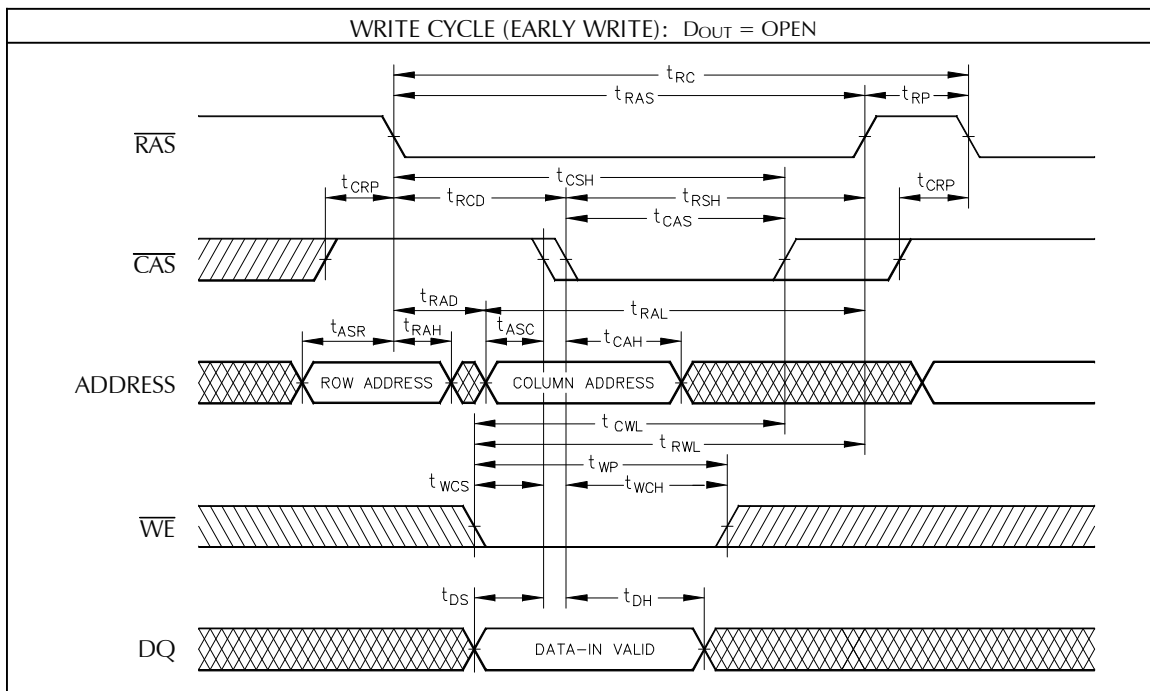
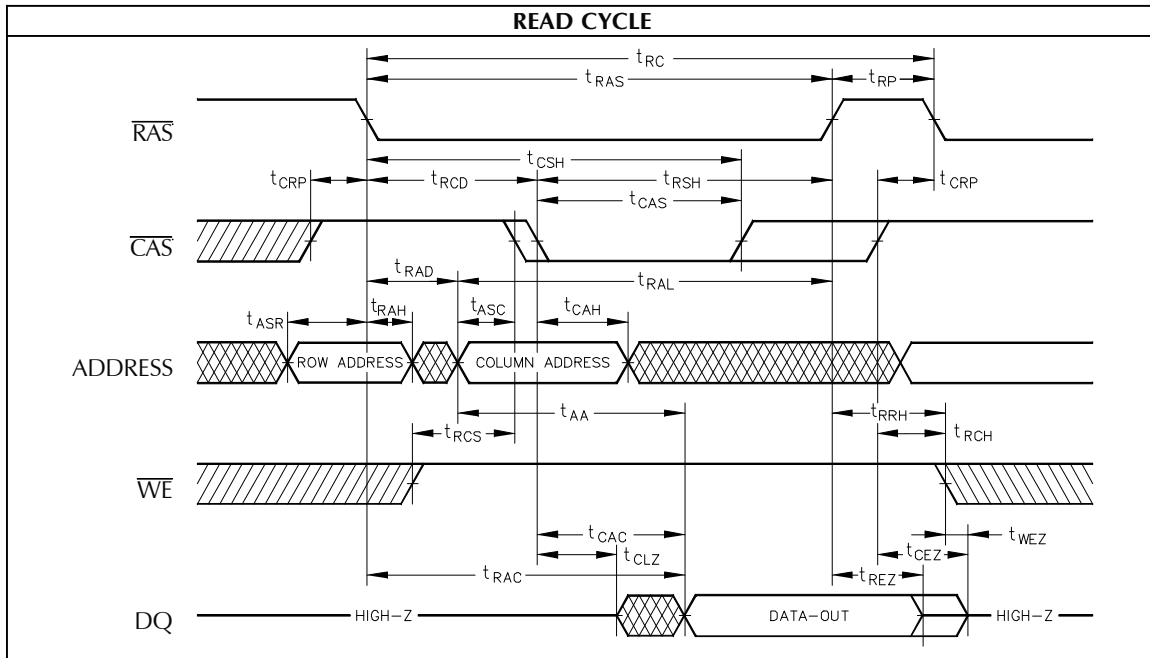
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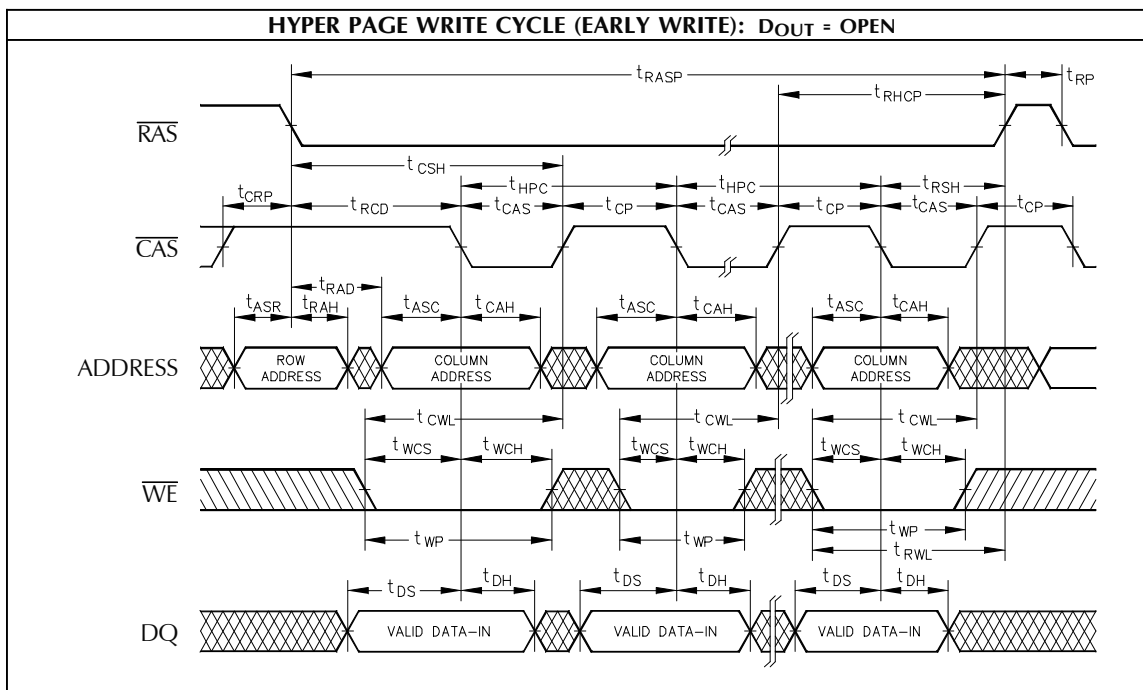
A.C. OPERATING AND CHARACTERISTICS ($V_{DD} = 5.0V \pm 10\%$, $T_A = 0^\circ C$ to $70^\circ C$) (Continued)									
No.	Symbol	Parameter	50ns		60ns		70ns		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	
37	tCP	$\overline{CAS}$ Precharge Time (Hyper Page Cycle)	8		10		10		ns
38	tCACP	Access Time from $\overline{CAS}$ (Hyper Page Cycle) ³		15		15		15	ns
39	tAAP	Access Time from Column Address (Hyper Page Cycle) ³		25		30		35	ns
40	tRASP	$\overline{RAS}$ Pulse Width (Hyper Page Cycle)	50	200,000	60	200,000	70	200,000	μs
41	tRHCP	$\overline{RAS}$ Hold Time From $\overline{CAS}$ Precharge	30		35		40		ns
42	tWRP	$\overline{WE}$ to $\overline{RAS}$ Precharge time ($\overline{C-B-R}$ Refresh)	10		10		10		ns
43	tWRH	$\overline{WE}$ to $\overline{RAS}$ Hold Time ($\overline{C-B-R}$ Refresh)	10		10		10		ns
44	tDOH	Output Data Hold Time	5		5		5		ns
45	tREZ	Output Buffer Turn Off Delay From $\overline{RAS}$ ^{6, 12}	3	13	3	15	3	20	ns
46	tWEZ	Output Buffer Turn Off Delay From $\overline{WE}$ ⁶	3	13	3	15	3	20	ns
47	tWED	$\overline{WE}$ to Data Delay	15		15		20		ns
48	tWPE	$\overline{WE}$ Pulse Width (Hyper Page Cycle)	5		5		5		ns

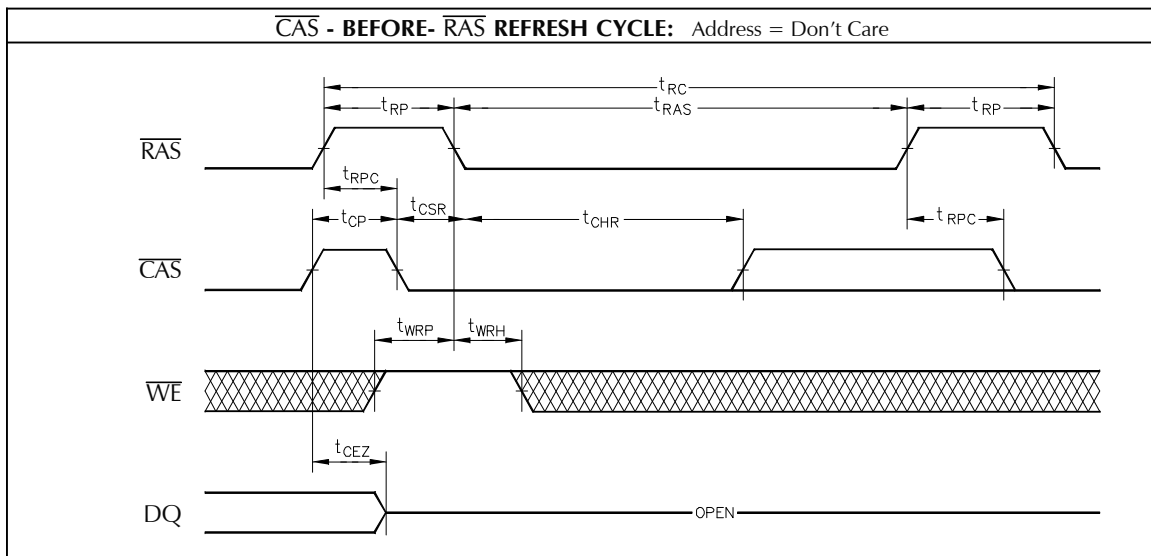
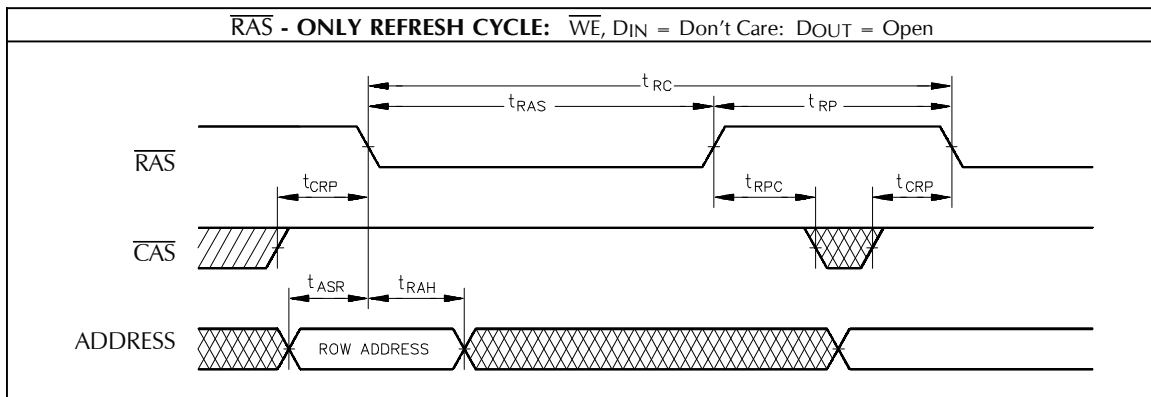
NOTES:

1. An initial pause of 200 μs is required after power-up followed by eight $\overline{RAS}$ refresh cycles ($\overline{RAS}$ -ONLY or CBR) before proper operation is assured.
2. V_{IH} (min.) and V_{IL} (max.) are reference levels for measuring timing of input signals. Transition times are measured between V_{IH} (min.) and V_{IL} (max.) and are assumed to be 5ns for all inputs.
3. Measured with the load equivalent to (2) two TTL load and 100pF.
4. Operation within the t_{RCD} (max.) limit ensures that t_{RAC} (max.) can be met. t_{RCD} (max.) is specified as a reference point only. If t_{RCD} is greater than the specified t_{RCD} (max.) limit, then access time is controlled exclusively by t_{CAC} .
5. Assumes that $t_{RCD} \geq t_{RCD}$ (max.).
6. This parameter defines the time at which the output achieves the open circuit conditions and is not referenced to V_{OL} or V_{OH} .
7. t_{WCS} , t_{RWC} , t_{CWD} and t_{AWD} are non restrictive operating parameters. They are included in the data sheet as electric characteristics only. If $t_{WCS} \geq t_{AWD}$ (min), the cycle is an early write cycle and the data output will remain high impedance for the duration of the cycle. If $t_{CWD} \geq t_{CWD}$ (min), $t_{RWD} \geq t_{RWD}$ (min), then the cycle is a read-modify-write cycle and the data output will contain the data read from the selected address. If neither of the above conditions is satisfied, the condition of the data out is indeterminate.
8. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
9. These parameters are referenced to the $\overline{CAS}$ leading edge in early write cycles.
10. Operation within the t_{RAD} (max) limit insures that t_{RAC} (max) can be met. t_{RAD} (max) is specified as a reference point only. If t_{RAD} is greater than the specified t_{RAD} (max) limit, then access time is controlled by t_{AA} .
11. t_{CEZ} (max), t_{REZ} (max) and t_{OEZ} (max) define the time at which the output achieves the open circuit condition and are not referenced to output voltage level.
12. If $\overline{RAS}$ goes high before $\overline{CAS}$ high going, the open circuit condition of the output is achieved by $\overline{CAS}$ high going. If $\overline{CAS}$ goes high before $\overline{RAS}$ high going, the open circuit condition of the output is achieved by $\overline{RAS}$ high going.
13. $t_{ASC} \geq 6ns$. Assume $t_T = 2.0ns$
14. It can get less $\overline{CAS}$ before $\overline{RAS}$ current loss if $t_{CHR} \geq t_{RAS}$ or $\overline{CAS} \leq 0.2V$ at $\overline{CAS}$ before $\overline{RAS}$ refresh mode.

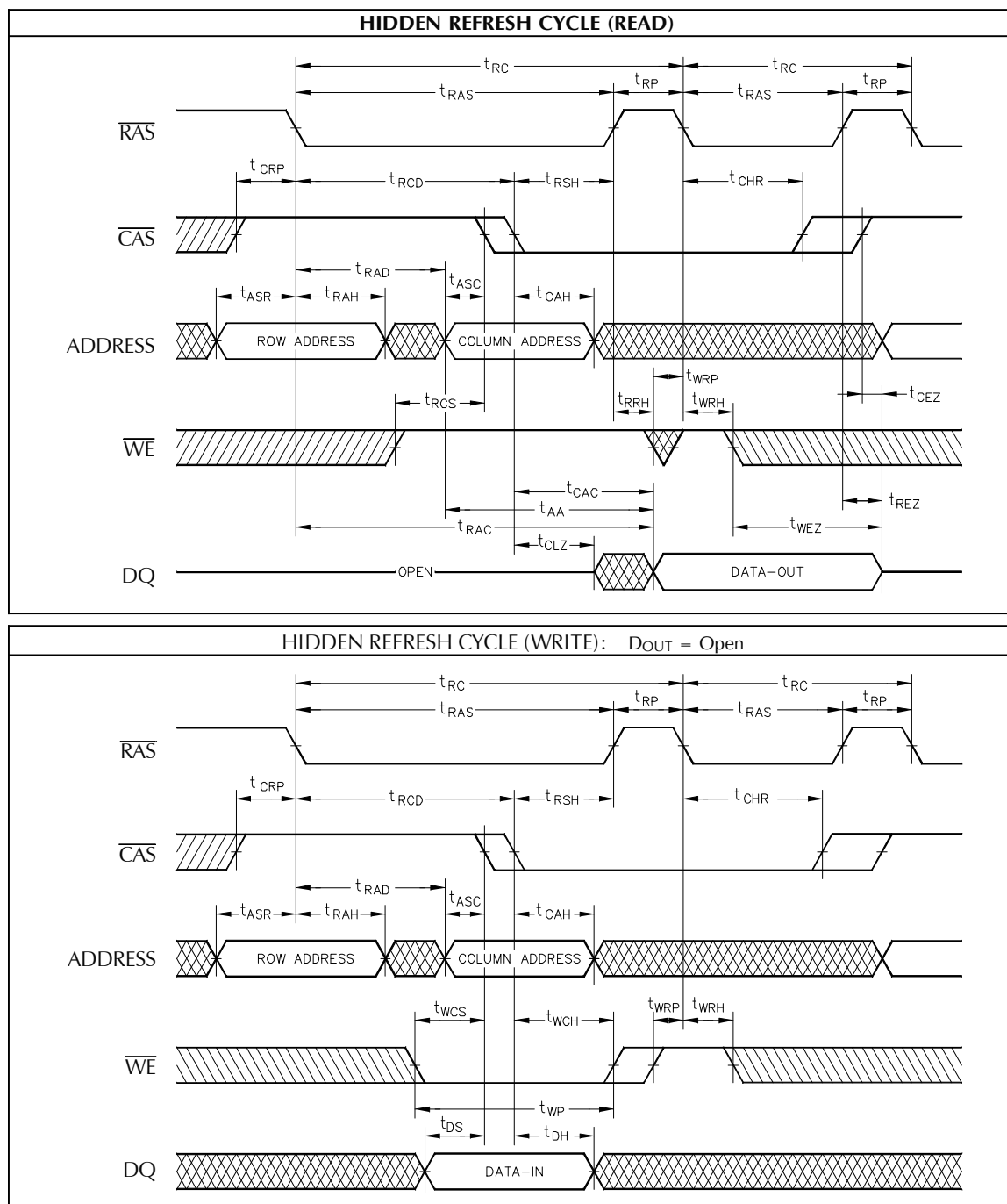
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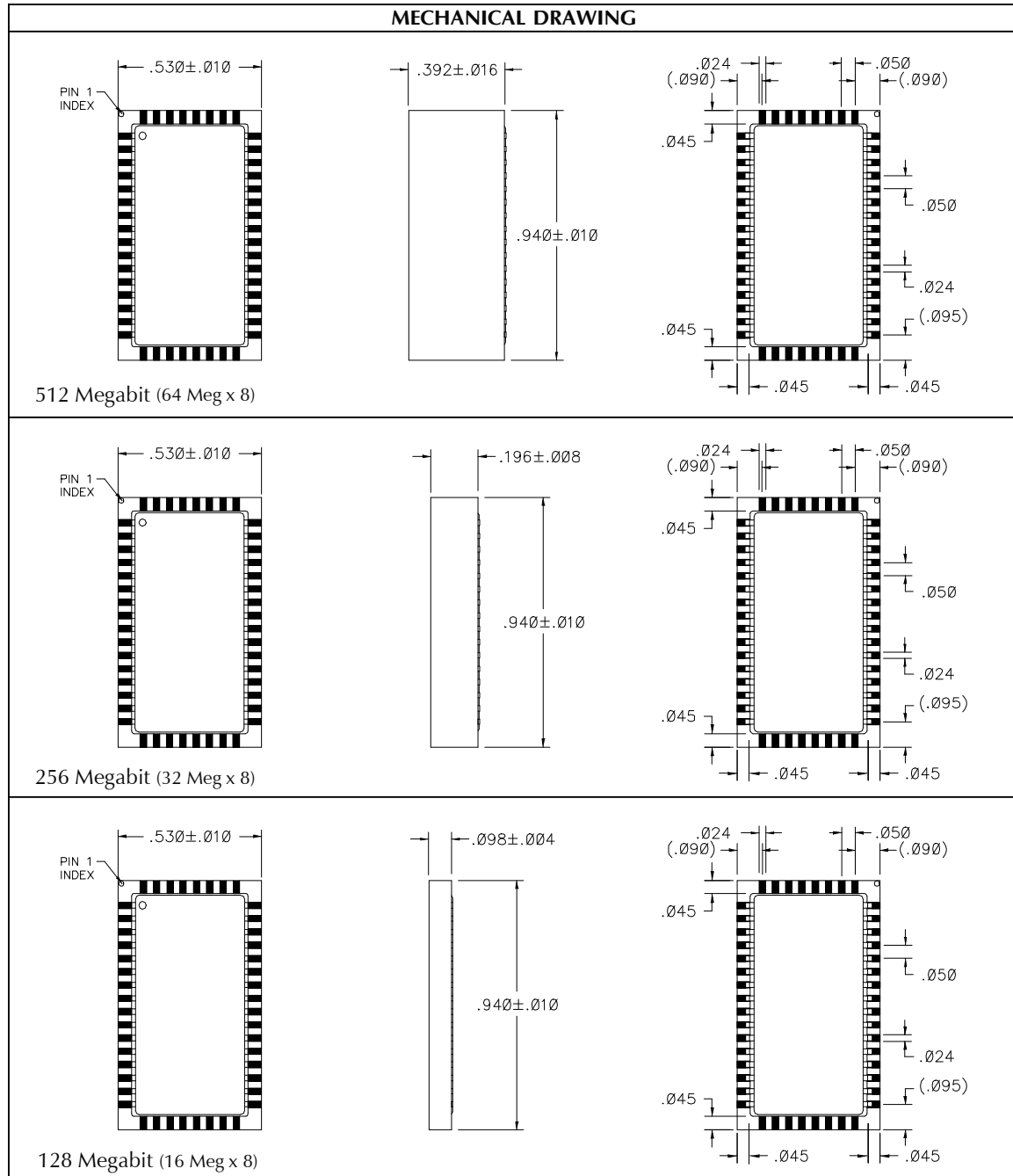


PRELIMINARY



PRELIMINARY

MECHANICAL DRAWING



ORDERING INFORMATION

DP	3ED	nM	X	4	Rn	Y5	- nn	C	
PREFIX	TYPE	MEMORY DEPTH	DESIG	MEMORY WIDTH	DESIG	PACKAGE	SPEED	GRADE	
								C	COMMERCIAL 0°C to +70°C
								50	50ns
								60	60ns
								70	70ns
						Y5			STACKABLE TSOP (T-STOCK)
					Rn			R	64 MEGABIT BASED 4K REFRESH
					Rn			R8	64 MEGABIT BASED 8K REFRESH
									MEMORY MODULE WITHOUT SUPPORT LOGIC
								128	128 MEG
								64	64 MEG
								32	32 MEG
									3.3 VOLT EDO DRAM

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